

# **Description**

The IRLML6401 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a

Battery protection or in other Switching application.



**SOT-23** 

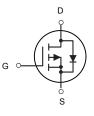
### **General Features**

 $V_{DS} = -20V, I_{D} = -5A$ 

 $R_{DS(ON)} < 45 m\Omega$  @  $V_{GS}$ =4.5V

## **Application**

High power and current handing capability
Lead free product is acquired
Surface mount package
PWM applications
Load switch
Power management



P-Channel MOSFET

# **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
IRLML6401	SOT-23	A5SHB	3000PCS

# Absolute Maximum Ratings (T<sub>A</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>D</sub> s	Drain-Source Voltage	-20	V
Vgs	Gate-Source Voltage	±12	V
Ι <sub>D</sub>	Drain Current-Continuous	-5	А
Ідм	Drain Current-Pulsed (Note 1)	-14	А
P <sub>D</sub>	Maximum Power Dissipation	1.31	W
T <sub>J</sub> ,T <sub>STG</sub>	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	120	°C/W



## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
$BV_{DSS}$	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-20			V	
$\triangle BV_{DSS}/\triangle T$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		-0.014		V/°C	
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-4.9A		35	45	mΩ	
	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}$ =-2.5V , $I_D$ =-3.4A		45	60		
		$V_{GS}$ =-1.8V , $I_D$ =-2A		65	85		
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> . In =-250uA	-0.4		-1.0	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS=VDS , ID =-250UA		3.95		mV/°C	
1	Drain Source Leekage Current	V <sub>DS</sub> =-16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			-1		
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			-5	uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 12V$ , $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	$V_{DS}$ =-5V , $I_{D}$ =-3A		12.8		S	
$Q_g$	Total Gate Charge (-4.5V)			10.2	14.3		
$Q_{gs}$	Gate-Source Charge	$V_{DS}$ =-15V , $V_{GS}$ =-4.5V , $I_{D}$ =-3A		1.89	2.6	nC	
$Q_gd$	Gate-Drain Charge			3.1	4.3		
$T_{d(on)}$	Turn-On Delay Time			5.6	11.2		
Tr	Rise Time	V <sub>DD</sub> =-10V , V <sub>GS</sub> =-4.5V ,		40.8	73		
$T_{d(off)}$	Turn-Off Delay Time	R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-3A		33.6	67	ns	
$T_f$	Fall Time			18	36		
C <sub>iss</sub>	Input Capacitance			857	1200		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		114	160	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			108	151		

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,4</sup>	V -V -0V Force Current	-	-	-4.9	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-14	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C			-1	V
t <sub>rr</sub>	Reverse Recovery Time	IF=-3A , di/dt=100A/μs ,	-	21.8	-	nS
$Q_{rr}$	Reverse Recovery Charge	T <sub>J</sub> =25°C		6.9		nC

#### Note:

<sup>1.</sup> The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

<sup>2.</sup>The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$ 

<sup>3.</sup> The power dissipation is limited by 150°C junction temperature

<sup>4.</sup> The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



## **Typical Characteristics**

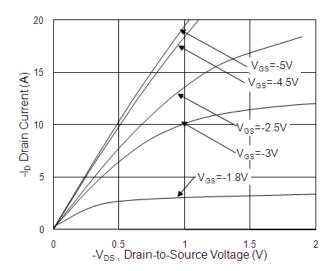


Fig.1 Typical Output Characteristics

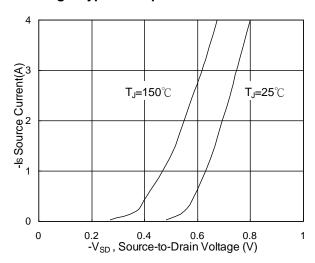


Fig.3 Forward Characteristics of Reverse

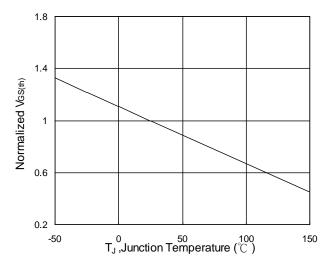


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

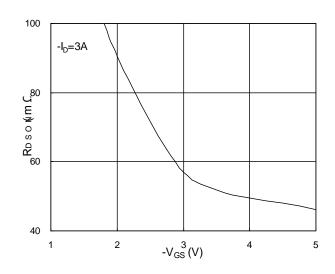


Fig.2 On-Resistance vs. G-S Voltage

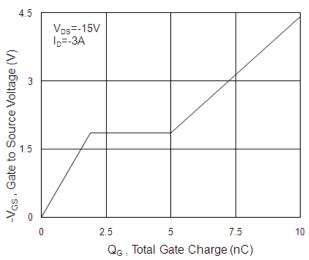


Fig.4 Gate-charge Characteristics

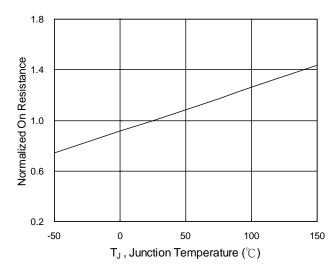
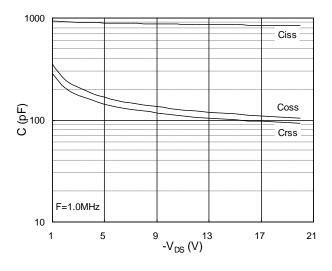


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





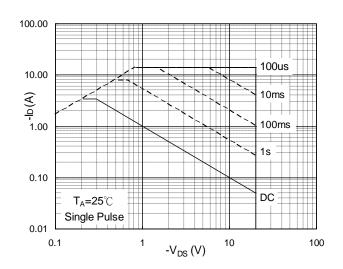


Fig.7 Capacitance

Fig.8 Safe Operating Area

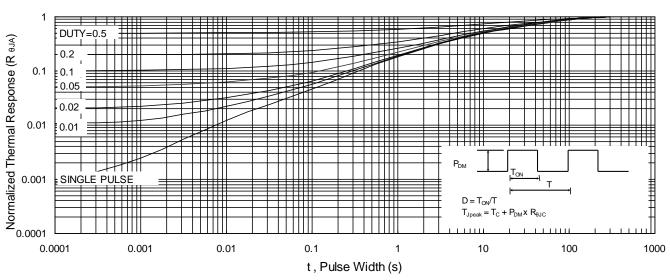
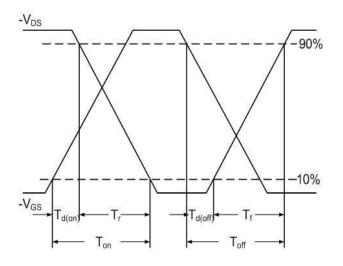


Fig.9 Normalized Maximum Transient Thermal Impedance



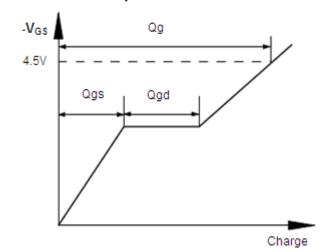
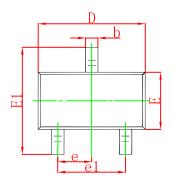


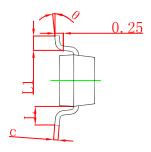
Fig.10 Switching Time Waveform

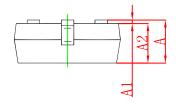
Fig.11 Gate Charge Waveform



# **SOT-23 Package Outline Dimensions**

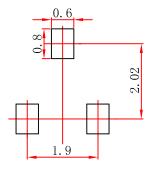






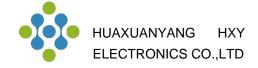
Symbol	Dimensions In Millimeters		Dimensions In Inches			
	Min	Max	Min	Max		
Α	0.900	1.150	0.035	0.045		
A1	0.000	0.100	0.000	0.004		
A2	0.900	1.050	0.035	0.041		
b	0.300	0.500	0.012	0.020		
С	0.080	0.150	0.003	0.006		
D	2.800	3.000	0.110	0.118		
E	1.200	1.400	0.047	0.055		
E1	2.250	2.550	0.089	0.100		
е	0.950	0 TYP 0.037 TYP		0.950 TYP		7 TYP
e1	1.800	2.000	0.071	0.079		
L	0.550	REF	0.022 REF			
L1	0.300	0.500	0.012	0.020		
θ	0°	8°	0°	8°		

# **SOT-23 Suggested Pad Layout**



### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
  3.The pad layout is for reference purposes only.



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